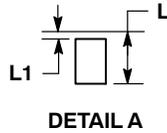
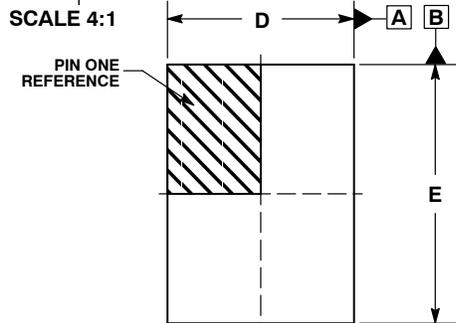
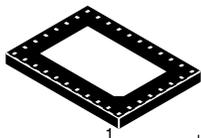
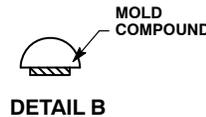
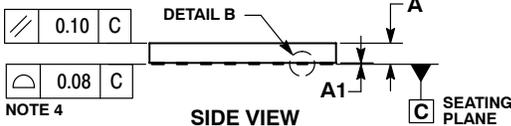


X2QFN34 3.1x4.3, 0.4P
CASE 722AL
ISSUE 0

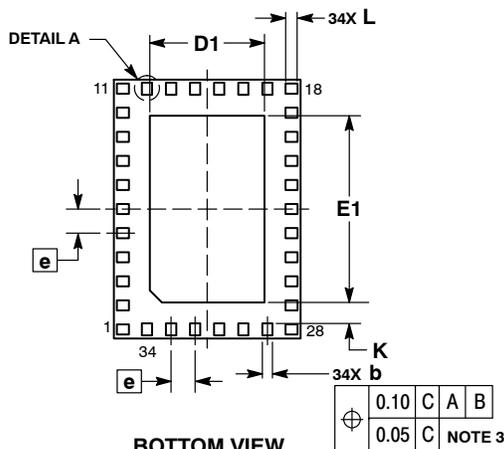
DATE 02 MAY 2017



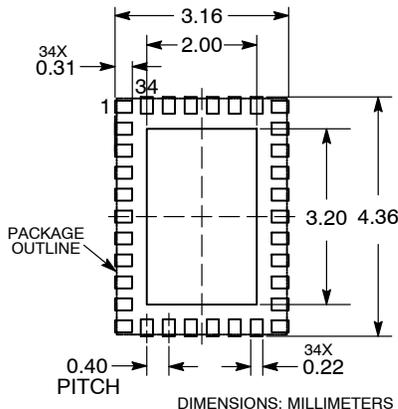
DETAIL A



DETAIL B



RECOMMENDED SOLDERING FOOTPRINT



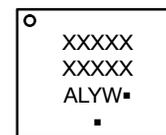
DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE PLATED TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.30	0.35	0.40
A1	---	---	0.05
b	0.12	0.17	0.22
D	3.00	3.10	3.20
D1	1.80	1.90	2.00
E	4.20	4.30	4.40
E1	3.00	3.10	3.20
e	0.40 BSC		
K	0.35 REF		
L	0.20	0.25	0.30
L1	0.05 REF		

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	X2QFN34 3.1X4.3, 0.4P	PAGE 1 OF 1

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